

PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
MOTOMUNE KODAMA	03/28/2019
HIDEKI TANAKA	03/28/2019
TAKAAKI SUZUKI	03/28/2019
JUNICHI SHIMOYAMA	03/28/2019
RECEIVING PARTY DATA	
Name:	HITACHI, LTD.
Street Address:	6-6, MARUNOUCHI 1-CHOME, CHIYODA-KU,
City:	TOKYO
State/Country:	JAPAN
Postal Code:	100-8280
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	16479274
CORRESPONDENCE DATA	
Fax Number:	(703)684-1157
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Phone:	703-684-1120
Email:	svannarath@mmpiaw.com
Correspondent Name:	MATTINGLY & MALUR, PC
Address Line 1:	1800 DIAGONAL ROAD
Address Line 2:	SUITE 210
Address Line 4:	ALEXANDRIA, VIRGINIA 22314
ATTORNEY DOCKET NUMBER:	ISO-12221
NAME OF SUBMITTER:	SHRINATH MALUR
SIGNATURE:	/Shrinath Malur/
DATE SIGNED:	07/19/2019
Total Attachments: 4	
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ASSIGNMENT

(譲渡証)

As a below named inventor, I hereby declare that:

IN CONSIDERATION of the sum of One Dollar (\$1.00) or the equivalent thereof, and other good and valuable consideration paid to me, by HITACHI, LTD., a corporation organized under the laws of Japan, located at 6-6, Marunouchi 1-chome, Chiyoda-ku, Tokyo 1008280, Japan, receipt of which is hereby acknowledged, I do hereby sell and assign to said HITACHI, LTD., its successors and assigns, all my right, title and interest, in and for the United States of America, in and to

METHOD OF PRODUCING SUPERCONDUCTOR

invented by me (if only one is named below) or us (if plural inventors are named below) and described in the application for United States Letters Patent therefor, executed on even date herewith, and all United States Letters Patent which may be granted therefor, and all divisions, continuations and extensions thereof, the said interest being the entire ownership of the said Letters Patent when granted, to be held and enjoyed by said HITACHI, LTD., its successors, assigns or other legal representatives, to the full end of term for which said Letters Patent may be granted, as fully and entirely as the same would have been held and enjoyed by me or us if this assignment and sale had not been made;

And I hereby agree to sign and execute any further documents or instruments which may be necessary, lawful, and proper in the prosecution of the above-named application or in the preparation and prosecution of any continuing, continuation-in-part, substitute, divisional, renewal, reviewed or reissue applications or in any amendment, extension, or interference proceedings, or otherwise to secure the title thereto in said assignee;

And I do hereby authorize and request the Commissioner of Patents to issue said Letters Patent to said HITACHI, LTD..

Signed on the date(s) indicated aside signatures:

INVENTOR(S)
(発明者フルネームサイン)

Date Signed
(署名日)

1) Motomune KODAMA
Motomune KODAMA

28 March 2019

2) Hideki TANAKA
Hideki TANAKA

INVENTOR(S)
(発明者フルネームサイン)

Date Signed
(署名日)

3) Takaaki Suzuki
Takaaki SUZUKI

3/28/2019

4) _____
Junichi SHIMOYAMA

ASSIGNMENT

(譲渡証)

As a below named inventor, I hereby declare that:

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invented by me (if only one is named below) or us (if plural inventors are named below) and described in the application for United States Letters Patent therefor, executed on even date herewith, and all United States Letters Patent which may be granted therefor, and all divisions, continuations and extensions thereof, the said interest being the entire ownership of the said Letters Patent when granted, to be held and enjoyed by said HITACHI, LTD., its successors, assigns or other legal representatives, to the full end of term for which said Letters Patent may be granted, as fully and entirely as the same would have been held and enjoyed by me or us if this assignment and sale had not been made;

And I hereby agree to sign and execute any further documents or instruments which may be necessary, lawful, and proper in the prosecution of the above-named application or in the preparation and prosecution of any continuing, continuation-in-part, substitute, divisional, renewal, reviewed or reissue applications or in any amendment, extension, or interference proceedings, or otherwise to secure the title thereto in said assignee;

And I do hereby authorize and request the Commissioner of Patents to issue said Letters Patent to said HITACHI, LTD..

,Signed on the date(s) indicated aside signatures:

INVENTOR(S)
(発明者フルネームサイン)

Date Signed
(署名日)

1) _____
Motomune KODAMA

2) Hideki Tanaka
Hideki TANAKA

March 28, 2019

INVENTOR(S)
(発明者フルネームサイン)

Date Signed
(署名日)

3)

Takaaki SUZUKI

4)

Junichi Shimoyama

Junichi SHIMOYAMA

March 28, 2019